ZettaCore and Ajinomoto to discuss GX-92 lamination with smooth copper at JIEP Annual Meeting

Denver, CO, USA and Tokyo, Japan – Mar 11, 2010. ZettaCore, Inc., a developer of materials for molecular electronics, and Ajinomoto Co., Inc. are presenting a paper at the 24th Japan Institute of Electronics Packaging (JIEP) Annual Meeting in Tokyo, Japan. In April 2009, both companies discussed e-less plating of copper on smooth dielectric at ICEP. This new information to be discussed at JIEP pertains to the lamination of dielectric material with copper, both with foil copper and electroplated copper.

ZettaCore has developed Molecular Interface™ (MI™) technology that enables adhesion of dielectric material with smooth copper. This nano treatment technology makes possible improvement in interconnect density and reduction in cost while utilizing conventional materials and processes.

MI process is very simple to implement and only requires dip tanks. Unlike other smooth interface technologies, MI process does not rely on an additional metal layer on copper. This easy to use method has the added advantage of process simplicity and does not require expensive etching techniques.

In addition, since there is no chemical etching of the copper surface, there are multiple benefits for PCB manufacturers as well as system designers:

1. Yield improvement
    a. Ease of material removal from smoother surface
    b. Reduction of shorting and voidance issues
2. Cost reduction
    a. Use of less expensive exposure technology
3. Finer line/space than is possible with chemical roughening
4. Improved impedance control
    a. Better trace/edge tolerances
5. Improved frequency performance
    a. Reduction of insertion loss
6. Reduced material and process cost

This new important MI technology has broad applications in:

1. FC BGA IC substrates
2. FC CSP IC substrates
3. Advanced CSP substrates
4. High-speed boards
5. HDI boards

Additional information can be found at www.zettacore.com